

EXECUTIVE SUMMARY OF April 2000 LBNL MEETING

LOCAL SUPPORTS

- Max fault pressure: 8 bar_a
- Max operating pressure: 4 bar_a
- Testing pressure: 10 bar for 1 hour

TASK	WHO	DEADLINE
3-5 supports: check stave stability with fixed supports	Vigeolas	FDR
3-5 supports: check material increase	Cuneo, IVW	15-05
3-5 supports: check impact of initial stave bowing on coverage and clearances	Cuneo, Barberis	15-05
Define stave C-C specs and QC (ultrasonic?)	Mora, Cuneo	PRR
Qualification of cooling terminations (irradiation, coolant exposure, pressure cycles, actions from supports)	Cuneo, Mora, Taylor, Anderssen	FDR
Thermal test on stave backup	Vigeolas	FDR
Thermal/pressure cycling of stave backup	Vigeolas	FDR
Omega QC (leak tightness) assessment	Mora	FDR
Review stave/sectors specs	Olcese, Gilchrease	15 May
Bare Local supports QC protocols	Cuneo, Gilchrease	FDR
Disk sector backup thermal tests	HYTEC	FDR
Impregnation assesement	Mora	FDR
Coolant corrosion on Al pipe	LBL, Vigeolas	FDR

GLOBAL SUPPORTS

TASK	WHO	DEADLINE
Envelope drawing of end cone	Cuneo	15/6/00
Simulation of overall assembly	HYTEC	Global support FDR
Design of end cone	HYTEC	Global support FDR
Improve barrel ring machining accuracy	IVW, Cuneo	Global support FDR
Define a baseline for disk mounts on frame		10/00
Evaluate a rigid mounting disk to frame (CTE tests)	LBNL, HYTEC	September PRR
Meet SCT to follow up pixel to SCT interfaces (support, thermal barrier, limits to differential pressure and assembly)	Anderssen, Olcese, Tappern	17 May
Prepare a document on Pixel envelopes and interfaces	Anderssen, Olcese	September PRR
Define services strain relieves	Anderssen, Cuneo	1/2001

MATERIAL

- Stave weight for structural design: 110 g

TASK	WHO	DEADLINE
Material update for physics simulation	Rossi	End May
Module material rebaseline	Rossi, Gilchrease	End May

SERVICES

TASK	WHO	DEADLINE
Define Al pigtails envelope	Ockenfels	15 May
Study of impact of Al pigtails on routing and fingers	Cuneo	15 June
Setup working group pixel-SCT on material for pipes and connections assessment	Tappern	May
Definition of baseline for cooling pipes and connections	Pixel-SCT working group	End 2000
Test of cooling inter-link (sector, stave end)	Anderssen, Thadome	FDR
Follow up heater thermal design and specifications	Olcese, Tappern	Cooling review
Feed back on heater control system requirements	Kevin	End April
Information on LBL service mockup to Cuneo	Anderssen	15 May
Barrel services mock-up	Cuneo, Ockenfels	September PRR
Define services up to PPB1	Anderssen, Olcese	Global supports FDR

ASSEMBLY AND TEST

- Milano CMM goes to SR building
- Modules cannot be tested without cooling

TASK	WHO	DEADLINE
Circulate SR building pixel area layout	Olcese	End of April
Feedback to ID assembly document	Olcese	May IDSG
Evaluate cable cost for SR building	Anderssen	
Check how to perform module functionality tests on barrel sub-assemblies with cooling	Olcese, Cuneo, Vigeolas	June cooling review
Need for evaporative system at assembly sites (size)	Gilchrease, Cuneo, Vigeolas	June cooling review
Check the available survey features available at CERN	Olcese	July
Circulate a first draft document on pixel survey and alignment	Olcese, Sinervo	July
Module alternative thermal check to IR camera	Vigeolas	PRR

B-LAYER INSTALLATION

TASK	WHO	DEADLINE
Define STC end-cap envelope	Olcese, Anderssen	Done
Preliminary information on beam pipe support aperture required for B-layer installation	Anderssen	Given to Ray Veness on February
Detail layout of how to assemble the B-layer in the space allocated	Anderssen	Beam pipe review
Conceptual design of services (tubes and cables) supports to rails	Anderssen	Beam pipe review
Patch panels: define locations	Anderssen	Beam pipe review
Access to B-layer installation area	TC (Bachy)	End of April

MODULE ASSEMBLY

TASK	WHO	DEADLINE
Work out assembly and test sequence of module on stave	Vigeolas, Ockenfels, Delpierre	FDR
Test thermal performances of new sector design with impregnated facings	LBNL	FDR
Collect Kapton properties	Boyd	Asap
FEA simulation of module assembly including additional glue ribbon sensor-chips	Cuneo	FDR
Circulate final version of module adhesive interfaces qualification plan	Olcese	Next week
Test of dummy modules with additional glue ribbon	Polina, Rossi	FDR

LOCAL SUPPORTS FDR PREPARATION

TASK	WHO	DEADLINE
Requirements (specifications, layout, material budget)	Olcese, Gilchrease	asap
Specifications for materials (potential suppliers)	Specific contributions	5/6/00
Specification for assembly (tools and procedures)	Cuneo, Vigeolas, Gilchrease	5/6/00
Design assesement: tests + simulations showing that specifications can be achieved	Frame prepared by Gilchrease + Specific contributions	5/6/00
Interface document	Anderssen	5/6/00
Drawings of parts	Cuneo, LBL	5/6/00
Drawings of assemblies	Cuneo, LBL	5/6/00
Presentations (short)	Specific contributions	5/6/00